## WD1039EB

## High Efficiency 2A continuous, 2.5A peak, 1MHz Synchronous Step Down Regulator

## Descriptions

The WD1039EB is a high efficiency, synchronous step down DC-DC convertor optimized for battery powered portable applications. It supports up to 2A continuous 2.5A peak output current. With a wide input voltage range of 2.7 V to 5.5 V , the device supports applications powered by single Li-ion battery with extended voltage range, two and three alkaline cell, 3.3 V and 5 V input voltage range. The WD1039EB operates at 1 MHz fixed switching frequency with Pulse-Width-Modulation (PWM) and enters Pulse-Skipping-Modulation (PSM) operation at light load current to maintain high efficiency over the entire load current range. 100\% duty cycle capability provides low dropout operation, extending battery life in portable systems.

The switching frequency is internally set at 1 MHz , allowing the use of tiny surface mount inductor and input/output capacitors.

The WD1039EB is available in SOT-23-5L package. Standard product is Pb -free and Halogen -free.

## Features

- Input voltage range
- Continue output current
- Switching frequency
- Efficiency
- Feedback reference voltage : 0.6V
- $100 \%$ duty cycle for low dropout operation
- Adjustable Output Voltage


## Applications

- Cellphones
- PADs
- STBs

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SOT-23-5L

Pin configuration (Top view)


| 1039 | $=$ Device code |
| :--- | :--- |
| EB | $=$ Package code |
| Y | $=$ Year code |
| W | $=$ Week code |
|  | Marking |

Order information

| Device | Package | Shipping |
| :---: | :---: | :---: |
| WD1039EB-5/TR | SOT-23-5L | 3000/Reel\&Tape |

## Typical applications



## Pin descriptions

| Symbol | Pin Number | Descriptions |
| :---: | :---: | :--- |
| EN | 1 | Enable, Active High |
| GND | 2 | Ground |
| LX | 3 | Switching signal output |
| VIN | 4 | Input Voltage |
| FB | 6 | Feedback |

## Block diagram



## Absolute maximum ratings

| Parameter | Symbol | Value | Unit |
| :--- | :---: | :---: | :---: |
| VIN pin voltage range | $\mathrm{V}_{\mathrm{IN}}$ | $-0.3 \sim 6.5$ | V |
| EN, FB pin voltage range | - | $-0.3 \sim \mathrm{~V}_{\mathrm{IN}}$ | V |
| SW pin voltage range (DC) | - | $-0.3 \sim \mathrm{~V}_{\mathrm{IN}}$ | V |
| Power Dissipation - SOT-23-5L (Note 1) | $\mathrm{P}_{\mathrm{D}}$ | 0.5 | W |
| Junction to Ambient Thermal Resistance - SOT-23-5L (Note 1) | $\mathrm{R}_{\text {өJA }}$ | 250 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| Junction temperature | $\mathrm{T}_{\mathrm{J}}$ | 150 | ${ }^{\circ} \mathrm{C}$ |
| Lead temperature(Soldering, 10s) | $\mathrm{T}_{\mathrm{L}}$ | 260 | ${ }^{\circ} \mathrm{C}$ |
| Operating ambient temperature | Topr | $-40 \sim 85$ | ${ }^{\circ} \mathrm{C}$ |
| Storage temperature | Tstg | $-55 \sim 150$ | ${ }^{\circ} \mathrm{C}$ |
| ESD Ratings | HBM | 8000 | V |
|  | MM | 400 | V |

These are stress ratings only. Stresses exceeding the range specified under "Absolute Maximum Ratings" may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

Note 1: Surface mounted on FR-4 Board using 1 square inch pad size, dual side, 10 copper

Electronics Characteristics ( $\mathrm{Ta}=25^{\circ} \mathrm{C}, \mathrm{V}_{\mathrm{IN}}=3.6 \mathrm{~V}, \mathrm{~V}_{\mathrm{EN}}=\mathrm{V}_{\mathrm{IN}}$, unless otherwise noted)

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Units |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Input Voltage Range | $\mathrm{V}_{\text {IN }}$ |  | 2.7 |  | 5.5 | V |
| Operating Supply Current | la | $\mathrm{V}_{\text {FB }}=60 \%$, lout $=0 \mathrm{~A}$ |  | 340 |  | uA |
| Standby Supply Current | la | $\mathrm{V}_{\text {FB }}=105 \%$, lout $=0 \mathrm{~A}$ |  | 80 |  | uA |
| Shutdown Supply Current | Ishon | $\mathrm{V}_{\text {EN }}=0 \mathrm{~V}, \mathrm{~V}_{\text {IN }}=4.2 \mathrm{~V}$ |  |  | 1 | uA |
| Feedback reference Voltage | $V_{\text {Fb }}$ |  | 0.588 | 0.60 | 0.612 | V |
| Line Regulation | $\triangle$ LINE | $\mathrm{V}_{\mathbb{1}}=2.7 \mathrm{~V}$ to 5.5 V lout $=10 \mathrm{~mA}$ |  | 0.05 | 1 | \%/V |
| Load Regulation | $\triangle$ LoAd | $\mathrm{l}_{\text {OUT }}=10 \mathrm{~mA}$ to 1 A |  | 1.4 |  | \% |
| Inductor Limit Current | lıim | $\mathrm{V}_{\text {IN }}=3.6 \mathrm{~V}$, $\mathrm{V}_{\text {OUT }}=90 \%{ }^{*} \mathrm{~V}_{\text {OUT }}$ | 2.6 |  |  | A |
| Oscillator Frequency | fosc | $\mathrm{V}_{\text {FB }}$ or $\mathrm{V}_{\text {OUt }}$ in regulation | 0.8 | 1 | 1.2 | MHz |
|  |  | $\mathrm{V}_{\text {FB }}$ or $\mathrm{V}_{\text {Out }}$ to GND |  | 250 |  | KHz |
| $\mathrm{R}_{\mathrm{DS} \text { (ON) }}$ of P-Channel FET | $\mathrm{R}_{\text {PFET }}$ | $\mathrm{I}_{\mathrm{sw}}=100 \mathrm{~mA}, \mathrm{~V}_{\mathrm{IN}}=3.6 \mathrm{~V}$ |  | 0.12 |  | $\Omega$ |
| $\mathrm{R}_{\mathrm{DS} \text { (ON) }}$ of N -Channel FET | $\mathrm{R}_{\text {NFET }}$ | $\mathrm{I}_{\mathrm{sw}}=-100 \mathrm{~mA}, \mathrm{~V}_{\mathbb{N}}=3.6 \mathrm{~V}$ |  | 0.08 |  | $\Omega$ |
| Feedback Leakage Current | Ifb |  |  |  | $\pm 30$ | nA |
| SW Leakage Current | ILsw | $\mathrm{V}_{\mathrm{IN}}=5 \mathrm{~V}, \mathrm{~V}_{\mathrm{sw}}=0 \mathrm{~V}$ or 5 V |  |  | $\pm 1$ | UA |
| EN Rising Threshold | $\mathrm{V}_{\text {ENH }}$ |  | 1.4 |  |  | V |
| EN falling Threshold | $V_{\text {ENL }}$ |  |  |  | 0.4 | V |
| EN Leakage Current | len | $\mathrm{V}_{\text {IN }}=5 \mathrm{~V}, \mathrm{~V}_{\text {EN }}=0 \mathrm{~V}$ or VIN |  |  | 1 | uA |
| Over Temperature Protection | Totp |  |  | 165 |  | ${ }^{\circ} \mathrm{C}$ |
| OTP Hysteresis |  |  |  | 30 |  | ${ }^{\circ} \mathrm{C}$ |
| Discharge Resistance | RLow | $\mathrm{V}_{\text {IN }}=5 \mathrm{~V}, \mathrm{~V}_{\text {EN }}=0 \mathrm{~V}$ |  | 200 |  | $\Omega$ |

Typical Characteristics $\left(\mathrm{Ta}=25^{\circ} \mathrm{C}, \mathrm{V}_{\mathrm{IN}}=3.6 \mathrm{~V}\right.$, unless otherwise noted)







WD1039EB


Load Transient
(Vin=3.6V, Vout=1.8V, I LOAD=0.04~1A)


80us/div

Turn off from Enable
(Vin=3.6V, Vout=1.8V, $\mathrm{I}_{\text {LOAD }}=1.8 \mathrm{~A}$ )


80us/div

## Load Transient

(Vin=5V, Vout=1.8V, ILOAD=0.14~1A)


Turn on from Enable (Vin=4.2V, Vout=2.4V, ILOAD=2A)


Vout short to GND transient (Vin=4V)


20us/div

## Operation Information

## PWM Control Mode

The WD1039EB step-down converter operates with typically 1 MHz fixed-frequency pulse width modulation (PWM) at moderate to heavy load currents. Both the main P-channel MOSFET and synchronous N -channel MOSFET switches are internal. During PWM operation, the converter uses a current-mode control scheme to achieve good line and load transient response. At the beginning of each clock cycle initiated by the clock signal, the main switch is turned on. The current flows from the input capacitor via the main switch through the inductor to the output capacitor and load. During this phase, the current ramps up until the PWM comparator trips and the control logic turn off the switch. After a dead time, which prevents shoot-through current, the synchronous switch is turned on and the inductor current ramps down. The current flows from the inductor and the output capacitor to the load. It returns back to the inductor through the synchronous switch.

The next cycle is initiated by the clock signal again turning off the synchronous switch and turning on the main switch.

## Pulse Skipping Mode (PSM)

At light loads, the inductor current may reach zero or reverse on each pulse. The synchronous switch is turned off by the current reversal comparator, IRCMP, and the switch voltage will ring. This is discontinuous mode operation, and is normal behavior for the switching regulator. At very light loads, the WD1039EB will automatically skip pulses in pulse skipping mode (PSM) operation to maintain output regulation.
of the oscillator is reduced to about 250 KHz . This frequency fold back ensures that the inductor current has more time to decay, thereby preventing runaway. The oscillator's frequency will progressively increase to 1 MHz when $\mathrm{V}_{\mathrm{FB}}$ rises above 0 V .

## Dropout Operation

The device starts to enter 100\% duty-cycle mode once the input voltage comes close to the nominal output voltage. In order to maintain the output voltage, the main switch is turned on $100 \%$ for one or more cycles. The output voltage will then be determined by the input voltage minus the voltage drop across the P-channel MOSFET and the inductor.

## Shutdown Mode

Drive EN to GND to place the WD1039EB in shutdown mode. In shutdown mode, the reference, control circuit, main switch, and synchronous switch turn off and the output becomes high impedance. Input current falls to $0.1 \mu \mathrm{~A}$ (Typ.) during shutdown mode.

## Over Temperature Protection (OTP)

As soon as the junction temperature ( $T_{J}$ ) exceeds $165^{\circ} \mathrm{C}$ (Typ.), the device goes into thermal shutdown. In this mode, the high-side and low-side MOSFET are turned off.

## Short-Circuit Protection

When the output is shorted to ground, the frequency

## Application Information

External component selection for the application circuit depends on the load current requirements. Certain tradeoffs between different performance parameters can also be made.

## Output Voltage Setting

The output voltage can be calculated as:

$$
\mathrm{V}_{\mathrm{OUT}}=0.6 \times\left(1+\frac{\mathrm{R} 1}{\mathrm{R} 2}\right)
$$

The external resistive divider is connected to the output, allowing remote voltage sensing as shown in figure as below. To minimize the current through the feedback divider network, R1 should be larger than $100 \mathrm{k} \Omega$. The sum of R1 and R2 should not exceed 1 $\mathrm{M} \Omega$, to keep the network robust against noise. An external feed forward capacitor $\mathrm{C}_{\text {FWD }}$, is required for optimum load transient response. The value of Cfwd should be in the range between 22 pF and 33 pF .

Route the FB line away from noise sources, such as the inductor or the LX line.


## Inductor Selection

The WD1039EB high switching frequency allows the use of a physically small inductor. The inductor ripple current is determined by

$$
\Delta I_{L}=\frac{V_{O U T}}{(f)(L)}\left(1-\frac{V_{O U T}}{V_{I N}}\right)
$$

Where $\Delta I_{L}$ is the peak-to-peak inductor ripple
current and $f$ is the switching frequency. The inductor peak-to-peak current ripple is typically set to be $40 \%$ of the maximum dc load current. Using this guideline and solving for $L$,

$$
L=\frac{V_{\text {OUT }}}{f\left(40 \% I_{\text {LOAD }(M A X)}\right)}\left(1-\frac{V_{\text {OUT }}}{V_{I N}}\right)
$$

It is important to ensure that the inductor is capable of handling the maximum peak inductor current, ILPK, determined by

$$
I_{L P K}=I_{L O A D(M A X)}+\frac{\Delta I_{L}}{2}
$$

## Inductor Core Selection

Different core materials and shapes will change the size/current and price/current relationship of an inductor. Toroid or shielded pot cores in ferrite or perm alloy materials are small and don't radiate much energy, but generally cost more than powdered iron core inductors with similar electrical characteristics. The choice of which style inductor to use often depends more on the price vs. size requirements and any radiated field EMI requirements than on what the WD1039EB requires to operate.

## Input Capacitor Selection

Capacitor ESR is a major contributor to input ripple in high-frequency DC-DC converters. Ordinary aluminum electrolytic capacitors have high ESR and should be avoided. Low-ESR tantalum or polymer capacitors are better and provide a compact solution for space constrained surface mount designs. Ceramic capacitors have the lowest overall ESR. The input filter capacitor reduces peak currents and noise at the input voltage source. Connect a low ESR bulk capacitor to the input. Select this bulk capacitor to meet the input ripple requirements and voltage rating rather than capacitance value. Use the following equation to calculate the maximum RMS input current:

$$
I_{\text {RMS }}=\frac{I_{\text {OUT }}}{V_{I N}} \sqrt{V_{\text {OUT }} \times\left(V_{\text {IN }}-V_{\text {OUT }}\right)}
$$

## Output Capacitor Selection

Ceramic capacitors with low-ESR values have the lowest output voltage ripple and are recommended. At nominal load current, the device operates in PWM mode, and the RMS ripple current is calculated as:

$$
I_{R M S C o u t}=V_{O U T} \times \frac{1-\frac{V_{O U T}}{V_{I N}}}{L \times f} \times \frac{1}{2 \times \sqrt{3}}
$$

At nominal load current, the device operates in PWM mode, and the overall output voltage ripple is the sum of the voltage spike caused by the output capacitor ESR plus the voltage ripple caused by charging and discharging the output capacitor:

$$
\Delta V=V_{O U T} \times \frac{1-\frac{V_{\text {OUT }}}{V_{I N}}}{L \times f} \times\left(\frac{1}{8 \times C_{O U T} \times f}+E S R\right)
$$

At light load currents, the converter operates in pulse skipping mode, and the output voltage ripple is dependent on the capacitor and inductor values. Larger output capacitor and inductor values minimize the voltage ripple in PSM operation and tighten dc output accuracy in PSM operation.

## PC Board Layout Considerations

A good circuit board layout aids in extracting the most performance from the WD1039EB. Poor circuit layout degrades the output ripple and the electromagnetic interference (EMI) or electromagnetic compatibility (EMC) performance.
The evaluation board layout is optimized for the WD1039EB. Use this layout for best performance. If this layout needs changing, use the following guidelines:

1. Use separate analog and power ground planes. Connect the sensitive analog circuitry (such as voltage divider components) to analog ground; connect the power components (such as input and output bypass capacitors) to power ground.

Connect the two ground planes together near the load to reduce the effects of voltage dropped on circuit board traces. Locate $\mathrm{Cin}_{\mathrm{I}}$ as close to the $\mathrm{V}_{\mathrm{IN}}$ pin as possible, and use separate input bypass capacitors for the analog.
2. Route the high current path from $\mathrm{C}_{\mathrm{IN}}$, through L , to the SW and PGND pins as short as possible.
3. Keep high current traces as short and as wide as possible.
4. Place the feedback resistors as close as possible to the FB pin to prevent noise pickup.
5. Avoid routing high impedance traces, such as FB, near the high current traces and components or near the switch node (LX).
6. If high impedance traces are routed near high current and/or the SW node, place a ground plane shield between the traces.


WD1039EB PCB Suggest Layout (Demo)


WD1039EB Demo Schematic

## Package outline dimensions

SOT-23-5L


| Symbol | Dimensions In Millimeters |  |  |
| :---: | :---: | :---: | :---: |
|  | Min. | Typ. | Max. |
| A | 1.050 | - | 1.250 |
| A1 | 0.000 | - | 0.100 |
| A2 | 1.050 | - | 1.150 |
| b | 0.300 | 0.400 | 0.500 |
| c | 0.100 | - | 0.200 |
| D | 2.820 | 2.900 | 3.020 |
| E | 1.500 | 1.600 | 1.700 |
| E1 | 2.650 | 2.800 | 2.950 |
| e | 1.800 | 0.950 Typ. |  |
| e1 | 0.300 | 1.900 | 2.000 |
| L | $0^{\circ}$ | - | 0.600 |
| $\theta$ |  | - | $8^{\circ}$ |

